IN THE CLAIMS:

Please amend the claims as follows:

1. (Canceled).

2. (Currently Amended) The duplexer as claimed in claim [[1]] 4, wherein the duplexer comprises a structure in which the ground line patterns on the die-attached layer and the underlying layer are connected by a via provided in the package.

3. (Currently Amended) The duplexer as claimed in claim [[1]] 4, wherein the ground line patterns have different widths and/or lengths.

4. (Currently Amended) ~~The duplexer as claimed in claim 1~~ A duplexer comprising:

two surface acoustic wave (SAW) filters having different center frequencies;

a phase matching circuit that matches phases of the two SAW filters;

a package in which the SAW filters and the phase matching circuit are housed, the package having a die-attached layer on which a chip of the SAW filters is facedown mounted; and

ground line patterns provided on the die-attached layer and an underlying layer that underlies the die-attached layer, the ground line patterns forming inductances,

wherein:

the two SAW filters have a plurality of stages composed of series resonators and parallel resonators; and

one of the ground line patterns connected to one of the parallel resonators shared by two stages is longer than another one of the ground line patterns connected to another one of the parallel resonators specifically used in one of the stages.

5. (Currently Amended) ~~The duplexer as claimed in claim 1~~ A duplexer comprising:

two surface acoustic wave (SAW) filters having different center frequencies;

a phase matching circuit that matches phases of the two SAW filters;

a package in which the SAW filters and the phase matching circuit are housed, the package having a die-attached layer on which a chip of the SAW filters is facedown mounted; and

ground line patterns provided on the die-attached layer and an underlying layer that underlies the die-attached layer, the ground line patterns forming inductances,

wherein:

the package has yet another layer on which a first phase matching line pattern that forms the phase matching circuit is formed; and

the ground wiring lines include a ground wiring line that runs above the first phase matching line pattern.

6. (Currently Amended) ~~The duplexer as claimed in claim 1~~ A duplexer comprising:

two surface acoustic wave (SAW) filters having different center frequencies;

a phase matching circuit that matches phases of the two SAW filters;

a package in which the SAW filters and the phase matching circuit are housed, the package having a die-attached layer on which a chip of the SAW filters is facedown mounted; and

ground line patterns provided on the die-attached layer and an underlying layer that underlies the die-attached layer, the ground line patterns forming inductances,

wherein the package comprises:

a first phase matching pattern layer on which a first phase matching line pattern of the phase matching circuit is formed;

a second phase matching pattern layer on which a second phase matching line pattern of the phase matching circuit is formed, the second phase matching pattern layer being located below the first phase matching pattern layer;

first, second and third ground patterns provided so that the first phase matching line pattern is interposed between the first and second ground patterns, and the second phase matching line pattern is interposed between the second and third ground patterns,

a distance between the first and second ground patterns being different from that between the second and third ground patterns.

7. (Original) The duplexer as claimed in claim 6, wherein the distance between the first and second ground patterns is shorter than the distance between the second and third ground patterns.

8. (Currently Amended) ~~The duplexer as claimed in claim 1~~ A duplexer comprising:

two surface acoustic wave (SAW) filters having different center frequencies;

a phase matching circuit that matches phases of the two SAW filters;

a package in which the SAW filters and the phase matching circuit are housed, the package having a die-attached layer on which a chip of the SAW filters is facedown mounted; and

ground line patterns provided on the die-attached layer and an underlying layer that underlies the die-attached layer, the ground line patterns forming inductances,

wherein the phase matching circuit comprises a phase matching line pattern having an impedance smaller than that of an external circuit coupled to the duplexer.

9. (Currently Amended) The duplexer as claimed in claim 6, wherein the first and second phase matching line ~~patters~~ patterns have crossing portions.

10. (Original) The duplexer as claimed in claim 6, wherein the second phase matching line pattern is longer than the first phase matching line pattern.

11. (Original) The duplexer as claimed in claim 6, wherein the first ground layer is interposed between the die-attached layer and the first phase matching line pattern.

12. (Currently Amended) ~~The duplexer as claimed in claim 1~~ A duplexer comprising:

two surface acoustic wave (SAW) filters having different center frequencies;

a phase matching circuit that matches phases of the two SAW filters;

a package in which the SAW filters and the phase matching circuit are housed, the package having a die-attached layer on which a chip of the SAW filters is facedown mounted; and

ground line patterns provided on the die-attached layer and an underlying layer that underlies the die-attached layer, the ground line patterns forming inductances,

wherein:

the ground line patterns include a receive ground line pattern involved in a receive system of the duplexer; and

the receive ground line pattern is connected to only a ground pattern on a cap mounting layer of the package and a footpad formed on a lowermost layer of the package.

13. (Original) The duplexer as claimed in claim 12, wherein:

the ground line patterns include a transmit ground line pattern involved in a transmit system of the duplexer; and

the transmit ground line pattern is connected to the receive ground pattern via only the footpad.

14. (Currently Amended) The duplexer as claimed in claim [[1]] 4, wherein the die-attached layer has flip-chip bonding pads connected to pads on a main surface of the chip.

15. (Currently Amended) ~~The duplexer as claimed in claim 1~~ A duplexer comprising:

two surface acoustic wave (SAW) filters having different center frequencies;

a phase matching circuit that matches phases of the two SAW filters;

a package in which the SAW filters and the phase matching circuit are housed, the package having a die-attached layer on which a chip of the SAW filters is facedown mounted; and

ground line patterns provided on the die-attached layer and an underlying layer that underlies the die-attached layer, the ground line patterns forming inductances,

wherein:

the phase matching circuit comprises a line pattern that runs on multiple layers of the package; and

ends of the line pattern are diagonally located on one of the multiple layers.

16. (Currently Amended) A duplexer comprising:

a chip having first and second surface acoustic wave (SAW) filters having different center frequencies;

a phase matching circuit that matches phases of the first and second SAW filters; and

a package in which the first and second SAW filters and the phase matching circuit are housed,

resonators of the first and second SAW filters being arranged side by side in a SAW propagating direction,

the chip having pads located further out than the resonators in the SAW propagating direction.

17. (Currently Amended) An electronic apparatus comprising:

an antenna;

a duplexer connected to the antenna; and

transmit and receive systems connected to the duplexer,

the duplexer comprising:

two surface acoustic wave (SAW) filters having different center frequencies;

a phase matching circuit that matches phases of the two SAW filters;

a package in which the SAW filters and the phase matching circuit are housed, the package having a die-attached layer on which a chip of the SAW filters is facedown mounted; and

ground line patterns provided on the die-attached layer and an underlying layer that underlies the die-attached layer, the ground line patterns forming inductances,

wherein:

the two SAW filters have a plurality of stages, composed of series resonators and parallel resonators; and

one of the ground line patterns connected to one of the parallel resonators shared by two stages is longer than another one of the ground line patterns connected to another one of the parallel resonators specifically used in one of the stages.

18. (Currently Amended) An electronic apparatus comprising:

an antenna;

a duplexer connected to the antenna; and

transmit and receive systems connected to the duplexer,

the duplexer comprising:

a chip having first and second surface acoustic wave (SAW) filters having different center frequencies;

a phase matching circuit that matches phases of the first and second SAW filters; and

a package in which the first and second SAW filters and the phase matching circuit are housed,

resonators of the first and second SAW filters being arranged side by side in a SAW propagating direction,

the chip having pads located further out than the resonators in the SAW propagating direction.